



**THE DATASHEET OF
CY29940AXCT**



2.5 V or 3.3 V, 200 MHz, 1:18 Clock Distribution Buffer

Features

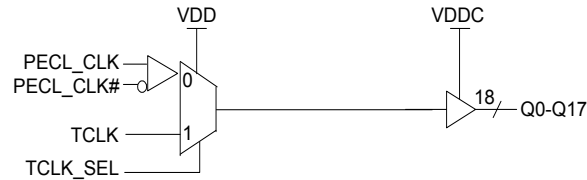
- 200 MHz clock support
- LVPECL or LVCMOS/LVTTL clock input
- LVCMOS/LVTTL compatible inputs
- 18 clock outputs: drive up to 36 clock lines
- 60 ps typical output-to-output skew
- Dual or single supply operation:
 - 3.3 V core and 3.3 V outputs
 - 3.3 V core and 2.5 V outputs
 - 2.5 V core and 2.5 V outputs
- Pin compatible with MPC940L, MPC9109
- Available in Commercial and Industrial temperature
- 32-pin TQFP package

Functional Description

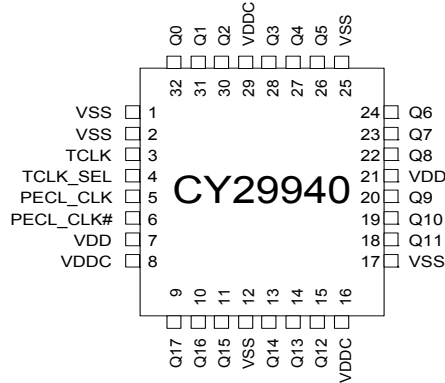
The CY29940 is a low-voltage 200 MHz clock distribution buffer with the capability to select either a differential LVPECL or a LVCMOS/LVTTL compatible input clock. The two clock sources can be used to provide for a test clock as well as the primary system clock. All other control inputs are LVCMOS/LVTTL compatible. The eighteen outputs are 2.5 V or 3.3 V LVCMOS/LVTTL compatible and can drive 50 Ω series or parallel terminated transmission lines. For series terminated transmission lines, each output can drive one or two traces giving the device an effective fanout of 1:36. Low output-to-output skews make the CY29940 an ideal clock distribution buffer for nested clock trees in the most demanding of synchronous systems.

For a complete list of related documentation, [click here](#).

Block Diagram



Pin Configuration



Pin Description

| Pin | Name | PWR | I/O [1] | Description |
|---|-----------|------|---------|--|
| 5 | PECL_CLK | | I, PU | PECL input clock |
| 6 | PECL_CLK# | | I, PD | PECL input clock |
| 3 | TCLK | | I, PD | External reference/test clock input |
| 9, 10, 11, 13, 14, 15, 18, 19, 20, 22, 23, 24, 26, 27, 28, 30, 31, 32 | Q(17:0) | VDDC | O | Clock outputs |
| 4 | TCLK_SEL | | I, PD | Clock Select Input. When LOW, PECL clock is selected and when HIGH TCLK is selected. |
| 8, 16, 29 | VDDC | | | 3.3 V or 2.5 V power supply for output clock buffers |
| 7, 21 | VDD | | | 3.3 V or 2.5 V power supply |
| 1, 2, 12, 17, 25 | VSS | | | Common ground |

Note

1. PD = Internal Pull-Down, PU = Internal Pull-up

Maximum Ratings

Exceeding the maximum ratings^[2] may impair the useful life of the device. User guidelines are not tested.

| | |
|--|---|
| Maximum input voltage relative to V_{SS} | $V_{SS} - 0.3\text{ V}$ |
| Maximum input voltage relative to V_{DD} | $V_{DD} + 0.3\text{ V}$ |
| Storage temperature | $-65\text{ }^{\circ}\text{C}$ to $+150\text{ }^{\circ}\text{C}$ |
| Operating temperature | $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ |
| Maximum ESD protection | 2 kV |

Maximum power supply 5.5 V

Maximum input current $\pm 20\text{ mA}$

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any voltage higher than the maximum rated voltages to this circuit. For proper operation, V_{in} and V_{out} should be constrained to the range:

$$V_{SS} < (V_{in} \text{ or } V_{out}) < V_{DD}$$

Unused inputs must always be tied to an appropriate logic voltage level (either V_{SS} or V_{DD}).

DC Parameters

$V_{DD} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$, $V_{DDC} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$, $T_A = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$

| Parameter ^[2] | Description | Conditions | Min | Typ | Max | Unit |
|--------------------------|--|--|----------------|-----|----------------|---------------|
| V_{IL} | Input low voltage | | V_{SS} | – | 0.8 | V |
| V_{IH} | Input high voltage | | 2.0 | – | V_{DD} | V |
| I_{IL} | Input low current ^[3] | | – | – | –200 | μA |
| I_{IH} | Input high current ^[3] | | – | – | 200 | μA |
| V_{PP} | Peak-to-peak input voltage PECL_CLK | | 500 | – | 1000 | mV |
| V_{CMR} | Common mode range ^[4] PECL_CLK | $V_{DD} = 3.3\text{ V}$ | $V_{DD} - 1.4$ | – | $V_{DD} - 0.6$ | V |
| | | $V_{DD} = 2.5\text{ V}$ | $V_{DD} - 1.0$ | – | $V_{DD} - 0.6$ | V |
| V_{OL} | Output low voltage ^[5, 6, 7] | $I_{OL} = 20\text{ mA}$ | – | – | 0.5 | V |
| V_{OH} | Output high voltage ^[5, 6, 7] | $I_{OH} = -20\text{ mA}$, $V_{DDC} = 3.3\text{ V}$ | 2.4 | – | – | V |
| | | $I_{OH} = -20\text{ mA}$, $V_{DDC} = 2.5\text{ V}$ | 1.8 | – | – | V |
| I_{DDQ} | Quiescent supply current | | – | 5 | 7 | mA |
| I_{DD} | Dynamic supply current | $V_{DD} = 3.3\text{ V}$, Outputs at 150 MHz, $C_L = 15\text{ pF}$ | – | 285 | – | mA |
| | | $V_{DD} = 3.3\text{ V}$, Outputs at 200 MHz, $C_L = 15\text{ pF}$ | – | 335 | – | |
| | | $V_{DD} = 2.5\text{ V}$, Outputs at 150 MHz, $C_L = 15\text{ pF}$ | – | 200 | – | |
| | | $V_{DD} = 2.5\text{ V}$, Outputs at 200 MHz, $C_L = 15\text{ pF}$ | – | 240 | – | |
| Z_{out} | Output impedance | $V_{DD} = 3.3\text{ V}$ | 8 | 12 | 16 | Ω |
| | | $V_{DD} = 2.5\text{ V}$ | 10 | 15 | 20 | |
| C_{in} | Input capacitance | | – | 4 | – | pF |

Thermal Resistance

| Parameter ^[8] | Description | Test Conditions | 32-pin TQFP | Unit |
|--------------------------|---|---|-------------|-----------------------------|
| θ_{JA} | Thermal resistance (junction to ambient) | Test conditions follow standard test methods and procedures for measuring thermal impedance, in accordance with EIA/JESD51. | 67 | $^{\circ}\text{C}/\text{W}$ |
| θ_{JC} | Thermal resistance (junction to case) | | 28 | $^{\circ}\text{C}/\text{W}$ |

Notes

- Multiple Supplies:** The Voltage on any input or I/O pin cannot exceed the power pin during power-up. Power supply sequencing is not required.
- Inputs have pull-up/pull-down resistors that effect input current.
- The VCMR is the difference from the most positive side of the differential input signal. Normal operation is obtained when the "High" input is within the VCMR range and the input lies within the VPP specification. Driving series or parallel terminated 50 Ω (or 50 Ω to $V_{DD}/2$) transmission lines
- Outputs driving 50 Ω transmission lines.
- See Figure 1 on page 5 and Figure 2 on page 5.
- 50% input duty cycle.
- These parameters are guaranteed by design and are not tested.

AC Parameters^[9]
 $V_{DD} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$, $V_{DDC} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$, $T_A = -40\text{ }^\circ\text{C}$ to $+85\text{ }^\circ\text{C}$

| Parameter | Description | Conditions | Min | Typ | Max | Unit | |
|----------------|---|---|-----------|-----|-----|------|----|
| F_{max} | Input frequency | | – | – | 200 | MHz | |
| t_{PD} | PECL_CLK to Q Delay ^[10, 11, 12] $\leq 150\text{ MHz}$ | $V_{DD} = 3.3\text{ V}, 85\text{ }^\circ\text{C}$ | t_{PHL} | 2.0 | – | 3.2 | ns |
| | | | t_{PLH} | 2.1 | – | 3.4 | |
| | | $V_{DD} = 3.3\text{ V}, 70\text{ }^\circ\text{C}$ | t_{PHL} | 1.9 | – | 3.1 | |
| | | | t_{PLH} | 2.0 | – | 3.2 | |
| | | $V_{DD} = 2.5\text{ V}, 85\text{ }^\circ\text{C}$ | t_{PHL} | 2.5 | – | 5.2 | |
| | | | t_{PLH} | 2.6 | – | 5 | |
| | | $V_{DD} = 2.5\text{ V}, 70\text{ }^\circ\text{C}$ | t_{PHL} | 2.5 | – | 5 | |
| | | | t_{PLH} | 2.6 | – | 5 | |
| t_{PD} | LVCMOS to Q Delay ^[10, 11, 12] $\leq 150\text{ MHz}$ | $V_{DD} = 3.3\text{ V}, 85\text{ }^\circ\text{C}$ | t_{PHL} | 1.9 | – | 3 | ns |
| | | | t_{PLH} | 2.0 | – | 3.2 | |
| | | $V_{DD} = 3.3\text{ V}, 70\text{ }^\circ\text{C}$ | t_{PHL} | 1.8 | – | 2.9 | |
| | | | t_{PLH} | 1.8 | – | 3.1 | |
| | | $V_{DD} = 2.5\text{ V}, 85\text{ }^\circ\text{C}$ | t_{PHL} | 2.5 | – | 4 | |
| | | | t_{PLH} | 2.5 | – | 4 | |
| | | $V_{DD} = 2.5\text{ V}, 70\text{ }^\circ\text{C}$ | t_{PHL} | 2.3 | – | 3.8 | |
| | | | t_{PLH} | 2.3 | – | 3.8 | |
| t_J | Total jitter | $V_{DD} = 3.3\text{ V} @ 150\text{ MHz}$ | – | – | 10 | ps | |
| F_{outDC} | Output duty cycle ^[10, 11, 13] | $F_{CLK} < 134\text{ MHz}$ | – | – | 55 | % | |
| | | $F_{CLK} > 134\text{ MHz}$ | – | – | 60 | | |
| T_{skew} | Output-to-output skew ^[10, 11] | $V_{DD} = 3.3\text{ V}$ | – | 60 | 150 | ps | |
| | | $V_{DD} = 2.5\text{ V}$ | – | – | 200 | | |
| $T_{skew(pp)}$ | Part-to-part skew ^[14] | PECL, $V_{DDC} = 3.3\text{ V}$ | – | – | 1.4 | ns | |
| | | PECL, $V_{DDC} = 2.5\text{ V}$ | – | – | 2.2 | | |
| $T_{skew(pp)}$ | Part-to-part skew ^[14] | TCLK, $V_{DDC} = 3.3\text{ V}$ | – | – | 1.2 | ns | |
| | | TCLK, $V_{DDC} = 2.5\text{ V}$ | – | – | 1.7 | | |
| $T_{skew(pp)}$ | Part-to-part skew ^[15] | PECL_CLK | – | – | 850 | ps | |
| | | TCLK | – | – | 750 | | |
| t_R/t_F | Output clocks rise/fall time ^[10, 11] | 0.7 V to 2.0 V, $V_{DDC} = 3.3\text{ V}$ | 0.3 | – | 1.1 | ns | |
| | | 0.5 V to 1.8 V, $V_{DDC} = 2.5\text{ V}$ | 0.3 | – | 1.2 | | |

Notes

9. Parameters are guaranteed by design and characterization. Not 100% tested in production. All parameters specified with loaded outputs.
10. Outputs driving $50\ \Omega$ transmission lines.
11. See [Figure 1 on page 5](#) and [Figure 2 on page 5](#).
12. Parameters tested @ 150 MHz.
13. 50% input duty cycle.
14. Across temperature and voltage ranges, includes output skew.
15. For a specific temperature and voltage, includes output skew.

Figure 1. LVCMOS_CLK CY29940 Test Reference for $V_{CC} = 3.3\text{ V}$ and $V_{CC} = 2.5\text{ V}$

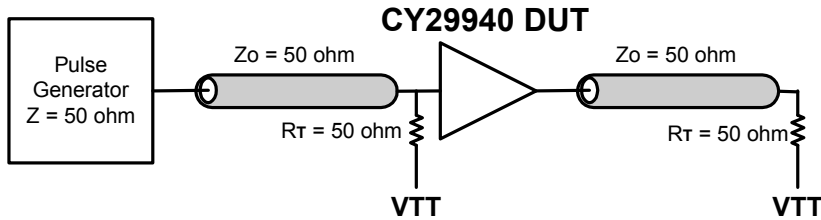


Figure 2. PECL_CLK CY29940 Test Reference for $V_{CC} = 3.3\text{ V}$ and $V_{CC} = 2.5\text{ V}$

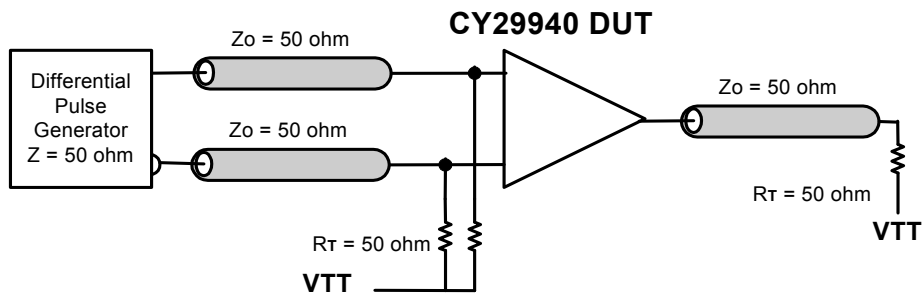


Figure 3. Propagation Delay (TPD) Test Reference

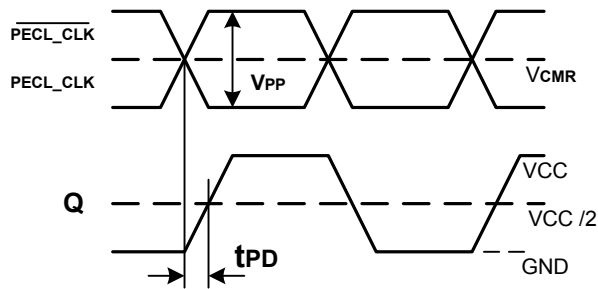


Figure 4. LVCMOS Propagation Delay (TPD) Test Reference

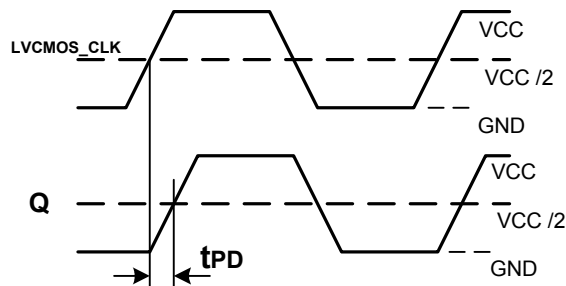


Figure 5. Output Duty Cycle (FoutDC)

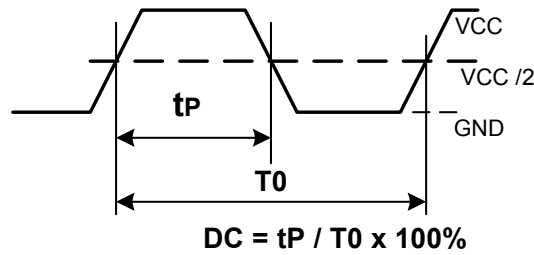
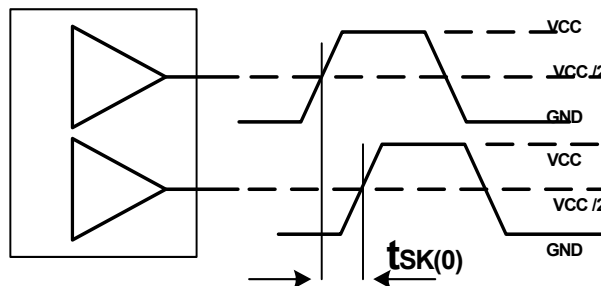


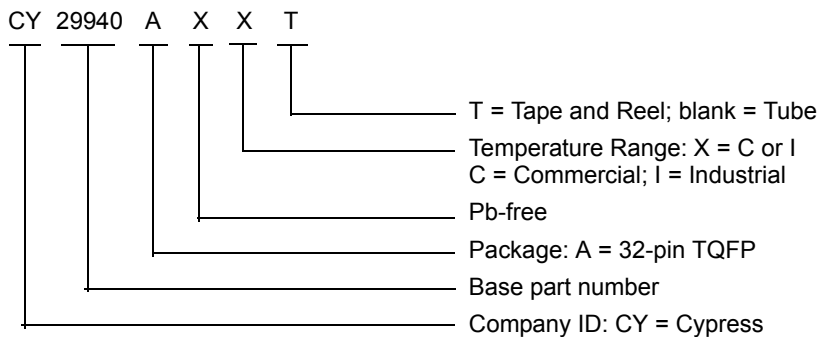
Figure 6. Output-to-Output Skew tsk(0)



Ordering Information

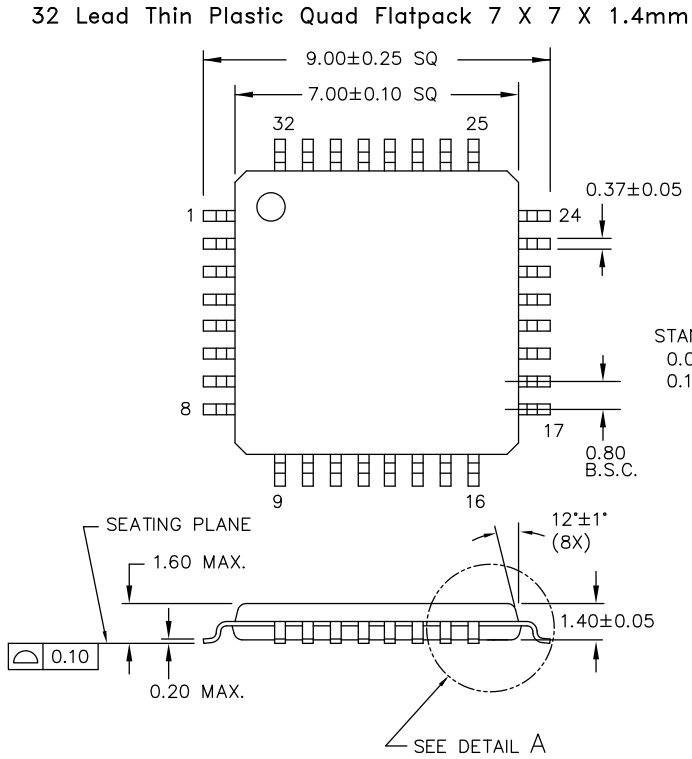
| Part Number | Package Type | Production Flow |
|----------------|-----------------------------|------------------------------|
| Pb-free | | |
| CY29940AXI | 32-pin TQFP | Industrial, -40 °C to +85 °C |
| CY29940AXIT | 32-pin TQFP – Tape and Reel | Industrial, -40 °C to +85 °C |
| CY29940AXC | 32-pin TQFP | Commercial, 0 °C to 70 °C |
| CY29940AXCT | 32-pin TQFP – Tape and Reel | Commercial, 0 °C to 70 °C |

Ordering Code Definitions

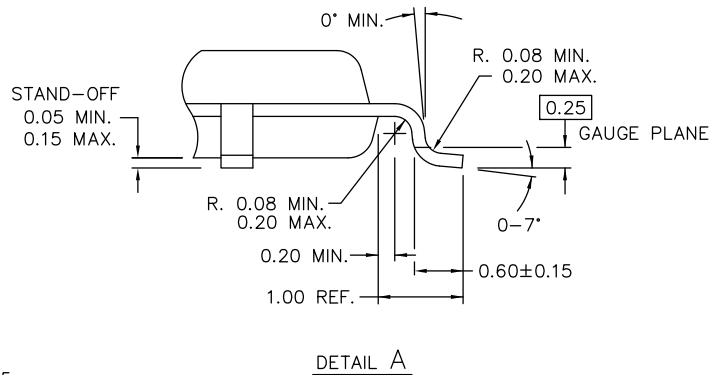


Package Drawing and Dimensions

Figure 7. 32-pin TQFP 7 × 7 × 1.4 mm A32.14



DIMENSIONS ARE IN MILLIMETERS
PKG WEIGHT: REFER TO PMDD SPEC



51-85088 *E

Acronyms

| Acronym | Description |
|---------|---|
| ESD | electrostatic discharge |
| I/O | input/output |
| TQFP | thin quad flat package |
| LVC MOS | low voltage complementary metal oxide semiconductor |
| LVPECL | low-voltage positive emitter-coupled logic |
| LVTTTL | low-voltage transistor-transistor logic |
| TQFP | thin quad flat pack |

Document Conventions

Units of Measure

| Symbol | Unit of Measure |
|--------|-----------------|
| °C | degree Celsius |
| kV | kilo Volts |
| MHz | Mega Hertz |
| μA | micro Amperes |
| mA | milli Amperes |
| mm | milli meter |
| mV | milli Volts |
| ns | nano seconds |
| Ω | ohms |
| % | percent |
| pF | pico Farad |
| ps | pico seconds |
| V | Volts |
| W | Watts |

Document History Page

| Document Title: CY29940, 2.5 V or 3.3 V, 200 MHz, 1:18 Clock Distribution Buffer | | | | |
|--|---------|------------|-----------------|--|
| Document Number: 38-07283 | | | | |
| Rev. | ECN No. | Issue Date | Orig. of Change | Description of Change |
| ** | 111094 | 02/01/02 | BRK | New data sheet |
| *A | 116776 | 08/15/02 | HWT | Incorporate results of final characterization using corporate methods, added output impedance on page 3 and added output duty cycle on page 4. Updated Ordering Information : Add commercial temperature range part numbers. |
| *B | 122875 | 12/21/02 | RBI | Add power up requirements to maximum rating information |
| *C | 448379 | See ECN | RGL | Add typical value for output-to-output skew Updated Ordering Information : Added Lead-free devices. |
| *D | 2899304 | 03/25/10 | BASH / KVM | Updated Ordering Information : Removed inactive parts. Updated Package Drawing and Dimensions . |
| *E | 3254185 | 05/11/2011 | CXQ | Added Ordering Code Definitions . Added Acronyms and Units of Measure . Updated to new template. |
| *F | 3548252 | 03/12/2012 | PURU | Changed LQFP to TQFP throughout document. |
| *G | 4586288 | 12/03/2014 | PURU | Updated Functional Description : Added "For a complete list of related documentation, click here ." at the end. Updated Package Drawing and Dimensions : Updated Figure 7 (spec 51-85088 – Changed revision from *D to *E). |
| *H | 4787038 | 06/04/2015 | TAVA | Updated to new template. Completing Sunset Review. |
| *I | 5258862 | 05/04/2016 | PSR | Added Thermal Resistance . Updated to new template. Completing Sunset Review. |
| *J | 5973872 | 11/22/2017 | AESATMP8 | Updated logo and Copyright. |

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